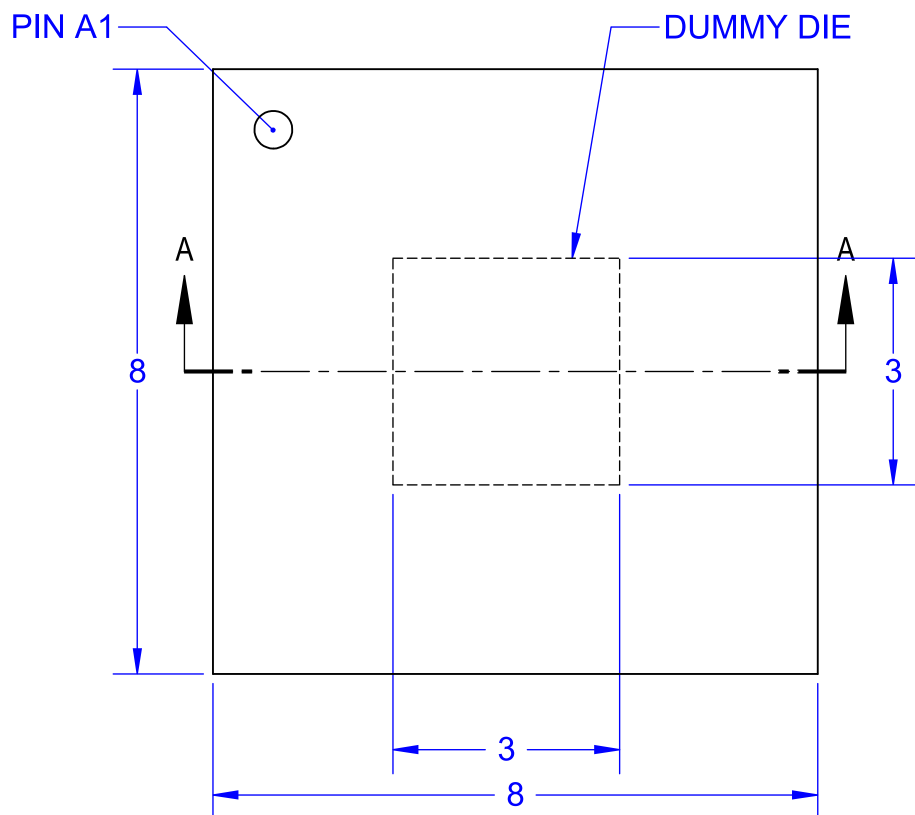
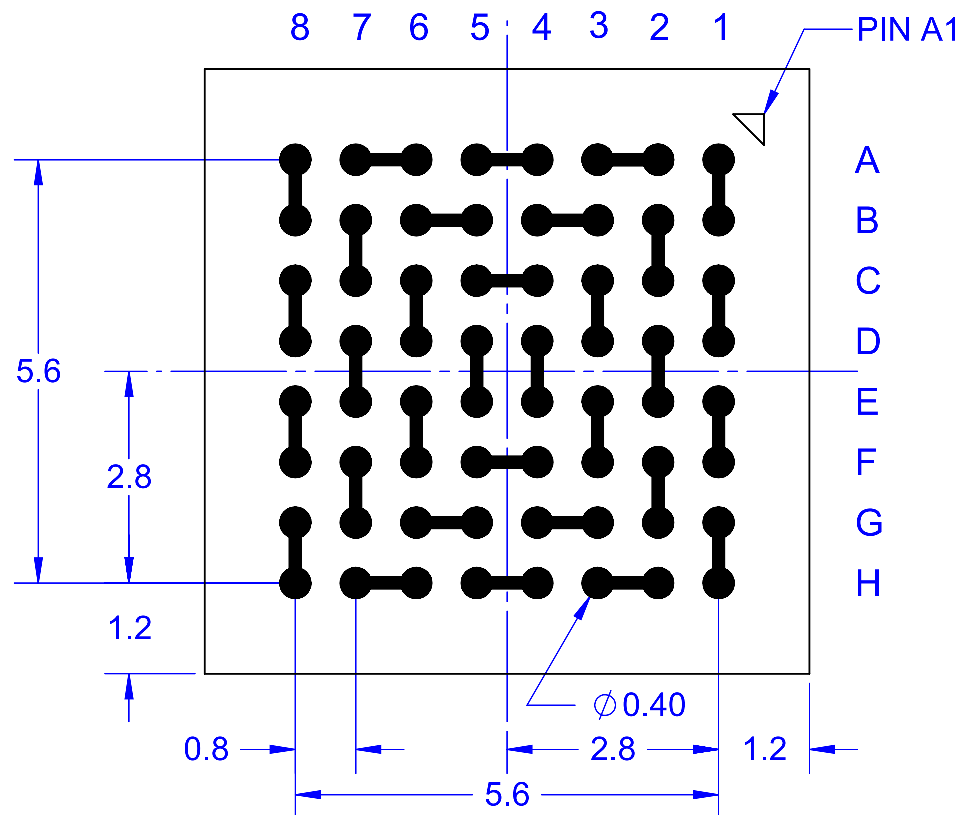
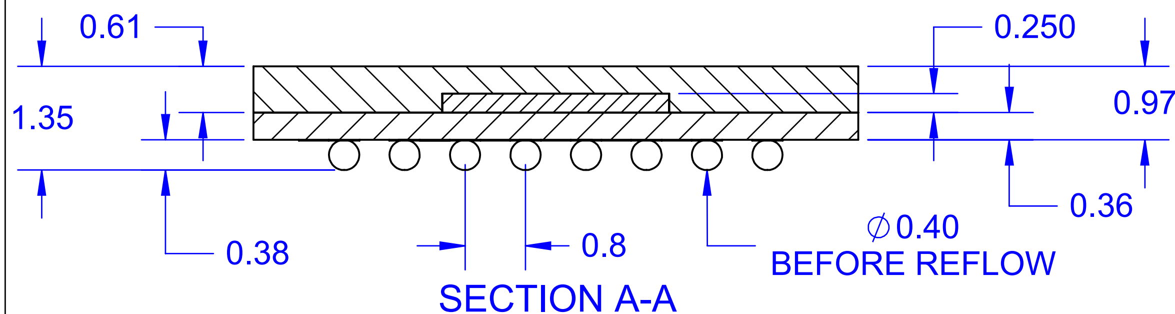


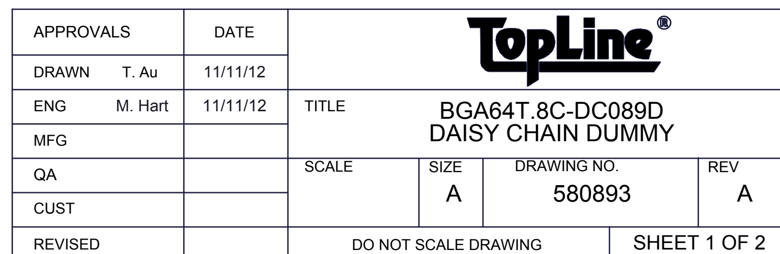




Notes: (Unless Otherwise Specified).
1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
4) SOLDER MASK DEFINED PAD OPENING: 0.32mm [13 MIL].
5) PAD Cu DIAMETER: 0.406mm [16 MIL].
6) SUBSTRATE MATERIAL: BT.
7) DUMMY DIE: 0.250mm [10 MIL] THICK.
8) DAISY CHAIN PATTERN (SEE PAGE 2).
9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA64T.8C-DC089D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LGA64T.8G-DC089D	NONE	YES	YES	YES
BGA64T.8-DC089D	Sn63/Pb37	NO	NO	YES



APPROVALS		DATE
DRAWN	T. Au	11/11/12
ENG	M. Hart	11/11/12
MFG		
QA		
CUST		
REVISED		

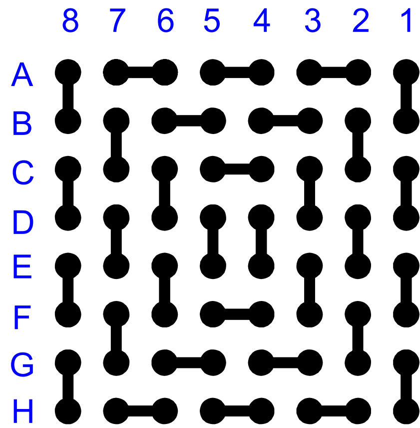
TopLine®

TITLE: BGA64T.8C-DC089D DAISY CHAIN DUMMY

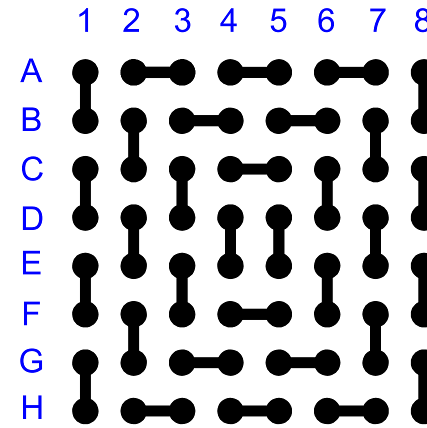
SCALE	SIZE	DRAWING NO.	REV
	A	580893	A

DO NOT SCALE DRAWING

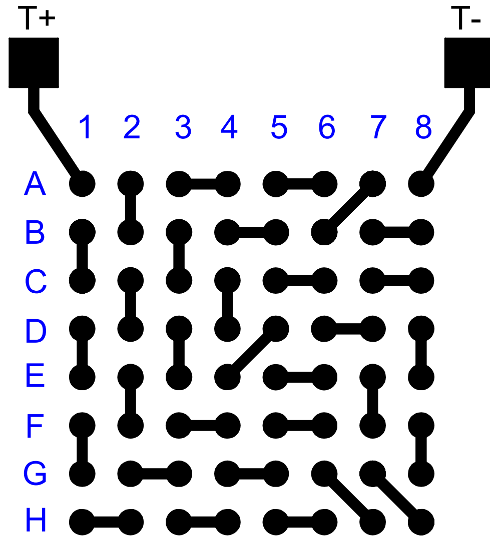
BALL VIEW



BOTTOM SIDE
(TOP X-RAY VIEW)

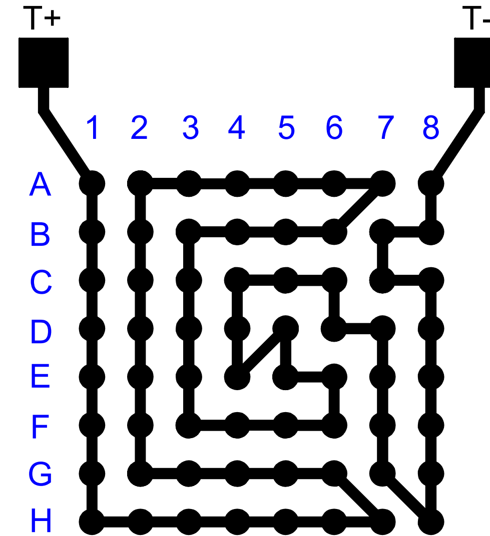


TOP VIEW



TEST VEHICLE BOARD

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:
1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
2) PCB Cu BALL PAD DIAMETER 0.406mm [16 MIL].
3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.320mm [13 MIL].

TopLine®

TITLE	BGA64T.8C-DC089D DAISY CHAIN DUMMY		
SCALE	SIZE A	DRAWING NO. 580893	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	